

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

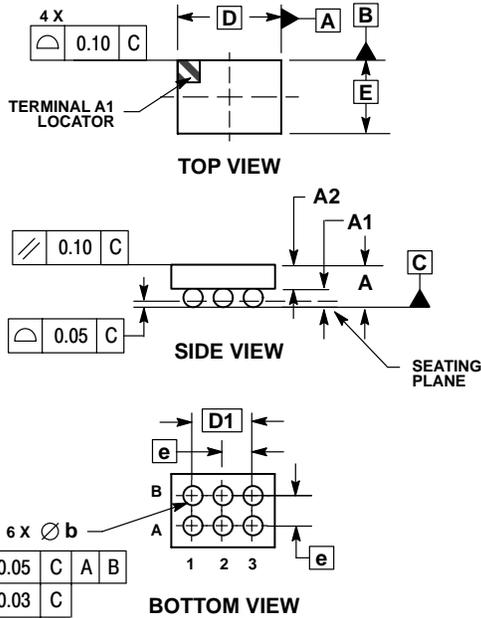


A1

SCALE 4:1

6 PIN FLIP-CHIP
1.72x1.22mm, 0.5 PITCH
 CASE 499J-01
 ISSUE O

DATE 05 FEB 2004



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.700
A1	0.210	0.270
A2	0.380	0.430
D	1.720 BSC	
E	1.220 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	1.000 BSC	

GENERIC MARKING DIAGRAM*



- xx = Specific Device Code
- A = Assembly Location
- WL, L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking.

DOCUMENT NUMBER:	98AON13950D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	6 PIN FLIP-CHIP, 1.72x1.22mm, 0.5 PITCH	PAGE 1 OF 2

